Supplementary Materials:

Ligand-Based Stability Changes in Duplex DNA Measured with a Microscale Electrochemical Platform

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Figure S1. Example calibration curve of platinum microheater/PRT.



Figure S2. Photo of the assembled platform for thermoelectric heating. (**a**) Device mounted on PCB with epoxy. Platform includes: (**b**) devices mounted on PCB above thermoelectric (TE) module with silicone heat-sink compound at the TE/glass interface, (**c**) wire bonds from contact pads of device electrodes to PCB, (**d**) wire bonds from contact pads of PRT to PCB, (**e**) leads to PRT, (**f**) lead to Au working electrode, (**g**) lead to Pt reference electrode, (**h**) lead to Pt counter electrode, (**i**) leads to TE module (under device), (**j**) Al block heat sink, and (**k**) screws used to secure PCB to Al block. RTV pillars under PCB are not shown.



Figure S3. (a) Full temperature program of platform in a melting experiment with 20 min of cooling at 0.3 V applied to thermoelectric, and (b) an expanded view of the melting portion of the experiment. The voltage was stepped by 0.25 V every 25 s from 0.3 V to –0.3 V.



Figure S4. Duplex melting curves on two different devices on the same day. (**a**) and (**b**) show results for Wafer 8, Device 17, trials 1 and 2; (**c**) and (**d**) show results for Wafer 8, Device 14, trials 1 and 2. All data were plotted in OriginPro 2016 and a Boltzmann function was used fit to the data to find T_m .